

ABSTRACT

An interconnection element of a spring (body) including a first resilient element with a first contact region and a second contact region and a first securing region and a second resilient element, with a third contact region and a second securing region. The second resilient element is coupled to the first resilient element through respective securing regions and positioned such that upon sufficient displacement of the first contact region toward the second resilient element, the second contact region will contact the third contact region. The interconnection, in one aspect, is of a size suitable for directly contacting a semiconductor device. A large substrate with a plurality of such interconnection elements can be used as a wafer-level contactor. The interconnection element, in another aspect, is of a size suitable for contacting a packaged semiconductor device, such as in an LGA package.